

One Technology Way, P.O. Box 9106, Norwood, MA 02062-9106, U.S.A.
Tel: 781.329.4700 www.analog.com
Fax: 781.461.3113 © 2005 Analog Devices, Inc. All rights reserved.

TABLE OF CONTENTS

Features	1	Pad Layout and Function Descriptions	5
Applications.....	1	Typical Performance Characteristics	6
General Description	1	Assembly Recommendations.....	9
Functional Block Diagram	1	Outline Dimensions	12
Revision History	2	Die Information.....	12
Electrical Specifications	3	Ordering Guide	12
Absolute Maximum Ratings.....	4		
ESD Caution.....	4		

REVISION HISTORY

7/05—Revision 0: Initial Version

ELECTRICAL SPECIFICATIONS

Minimum/maximum $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$, $T_{\text{AMBIENT}} = -40^{\circ}\text{C}$ to $+95^{\circ}\text{C}$; typical $V_{CC} = 3.3 \text{ V}$, $T_{\text{AMBIENT}} = 25^{\circ}\text{C}$, unless otherwise noted.

Table 1.

Parameter	Conditions	Min	Typ	Max	Unit
DYNAMIC PERFORMANCE					
Bandwidth (BW) ¹	−3 dB	1.9	2.5		GHz
Total Input Referred RMS Noise (I_{RMS})	$C_D = 0.8 \text{ pF}$, dc to 2.1 GHz		315	485	nA
Total Input Referred RMS Noise (I_{RMS})	$C_D = 0.6 \text{ pF}$, dc to 2.1 GHz		300		nA
Small Signal Transimpedance (Z_T) ¹	100 MHz, differential	2700	4400	6200	V/A
	100 MHz, single-ended	1350	2200	3100	V/A
Low Frequency Cutoff	CAP = open, $I_{\text{IN}} = 20 \mu\text{A}$		20		kHz
	CAP = 1 nF, $I_{\text{IN}} = 20 \mu\text{A}$		1.0		kHz
Output Return Loss	DC to 3.5 GHz, differential		−26	−20	dB
Input Overload Current	ER = 10 dB, at 95°C ¹	2.1 ¹	4.3		mA p-p
Maximum Differential Output Swing	$I_{\text{IN, P-P}} = 2.0 \text{ mA}$	170	260	375	mV p-p
Output Data Transition Time	$I_{\text{IN, P-P}} = 1.0 \text{ mA}$; 20% to 80% rise/fall time		60		ps
PSRR	$I_{\text{IN}} = 0 \text{ mA}$, <10 MHz		39		dB
Group Delay Variation	1.0 GHz to 3.0 GHz		50		ps
Transimpedance Ripple	50 MHz to 1.0 GHz, single-ended		0.93		dB
Deterministic Jitter	$10 \mu\text{A} < I_{\text{IN, P-P}} \leq 100 \mu\text{A}$, K28.5 @ 3.2 Gbps		16		ps p-p
	$100 \mu\text{A} < I_{\text{IN, P-P}} \leq 2.0 \text{ mA}$, K28.5 @ 3.2 Gbps		25		ps p-p
	$10 \mu\text{A} < I_{\text{IN, P-P}} \leq 2.0 \text{ mA}$, PRBS 2 ³¹ − 1 at OC48 (FEC)		38		ps p-p
Linear Output Range	Differential, <1 dB compression		210		mV p-p
Linear Input Current Range	Single-ended, <1 dB compression		53		$\mu\text{A p-p}$
DC PERFORMANCE					
Power Dissipation	$I_{\text{IN, AVE}} = 0 \text{ mA}$		70	110	mW
Input Voltage	Compliance voltage		0.85		V
Output Common-Mode Voltage	DC (50 Ω) terminated to VCC		$V_{CC} - 0.12$		V
Output Impedance	Single-ended		50		Ω
PD FILTER Resistance	R_F		200		Ω
PD FILTER Capacitance	C_F		20		pF
RSSI Gain	$I_{\text{IN, AVE}} = 5 \mu\text{A}$ to 1 mA		0.85		V/mA
RSSI Offset	$I_{\text{IN, AVE}} = 10 \mu\text{A}$		8.0		mV
RSSI Accuracy	$5 \mu\text{A} < I_{\text{IN, P-P}} \leq 20 \mu\text{A}$		± 7		%
	$20 \mu\text{A} < I_{\text{IN, P-P}} \leq 1 \text{ mA}$		± 3		%

¹ An equivalent $I_{\text{IN, P-P}} = 13 \mu\text{A}$ current signal is applied to the TIA input. No input capacitor is applied.

ABSOLUTE MAXIMUM RATINGS

Table 2.

Parameter	Rating
Supply Voltage (VCC to GND)	5 V
Maximum Voltage to All Input and Output Signal Pins	VCC + 0.4 V
Minimum Voltage to All Input and Output Signal Pins	GND – 0.4 V
Maximum Input Current	10 mA
Storage Temperature Range	–65°C to +125°C
Operating Ambient Temperature Range	–40°C to +95°C
Maximum Junction Temperature	125°C
Die Attach Temperature (<30 sec)	410°C

Stresses above those listed under Absolute Maximum Rating may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although this product features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



PAD LAYOUT AND FUNCTION DESCRIPTIONS

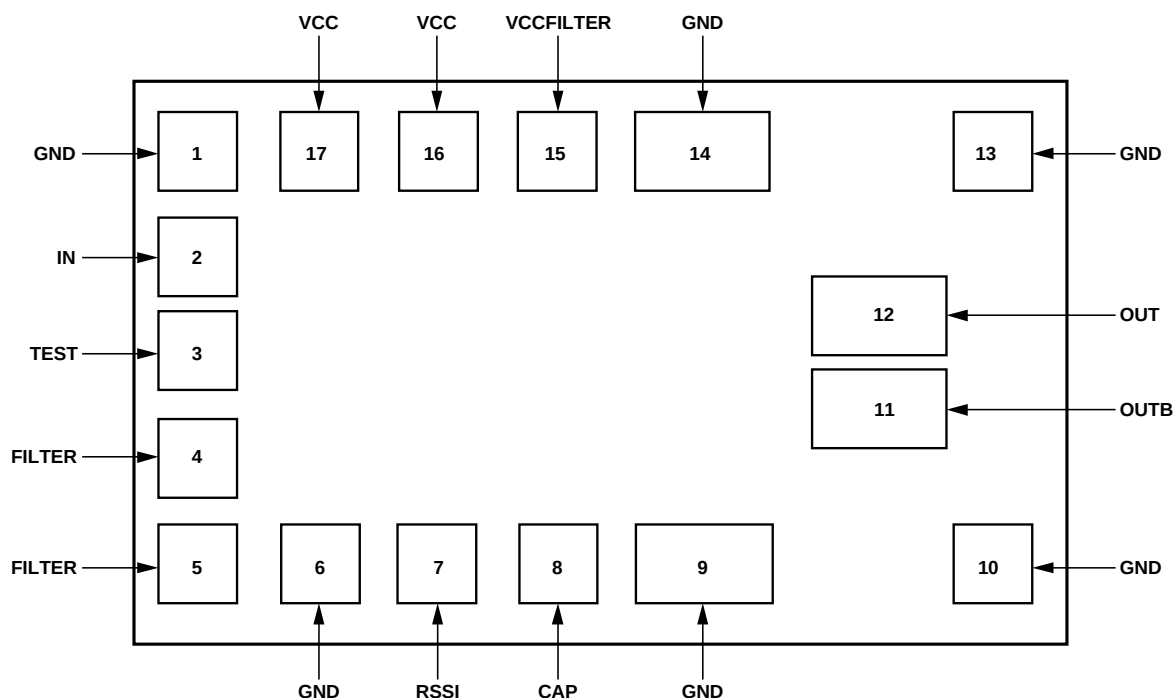


Figure 2. Pad Layout

04945-002

Table 3. Pad Function Descriptions

Pad No.	Mnemonic	Pin Type ¹	Description
1	GND	P	Ground. (Input return.)
2	IN	AI	Current Input. Bond directly to a photodiode (PD) anode.
3	TEST	AI	Test Probe Pad. Do not connect.
4, 5	FILTER	AO	Filter Output. Pad 4 and Pad 5 are metal connected. Optional bond to a PD cathode.
6	GND	P	Ground.
7	RSSI	AO	Voltage Output. Provides average input current monitoring. If not used, connect to ground.
8	CAP	AI	Low Frequency Cutoff (LFC) Setpoint. For SONENT applications, see Figure 10 and contact sales for assembly details.
9, 10, 13, 14	GND	P	Ground. (Output return.)
11	OUTB	AO	Negative Output, CML, On-Chip 50 Ω Termination (AC or DC Termination).
12	OUT	AO	Positive Output, CML, On-Chip 50 Ω Termination (AC or DC Termination).
15	VCCFILTER	P	On-Chip Filter Supply. Connect to VCC to Enable On-Chip RC Filter (200 Ω , 20 pF). Leave unconnected if not used.
16, 17	VCC	P	3.3 V Supply. Place a 200 pF, RF decoupling capacitor close to the power pad to reduce the power noise.

¹ P = power; AI = analog input; and AO = analog output.

TYPICAL PERFORMANCE CHARACTERISTICS

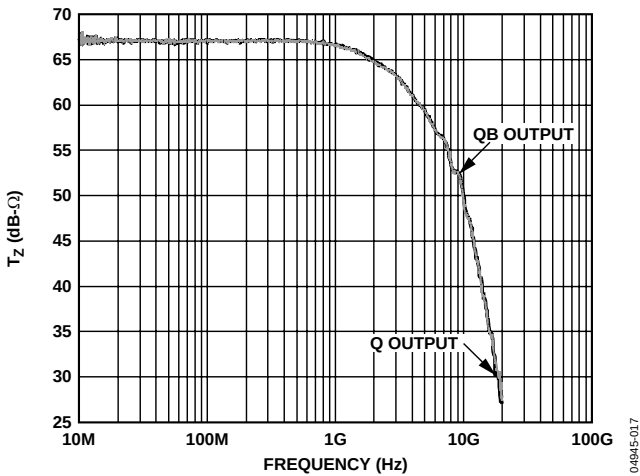


Figure 3. Single-Ended Transimpedance vs. Frequency

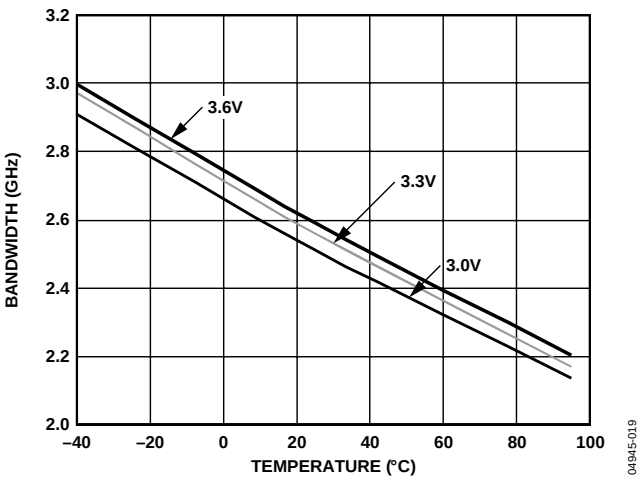


Figure 6. Bandwidth vs. VCC and Temperature

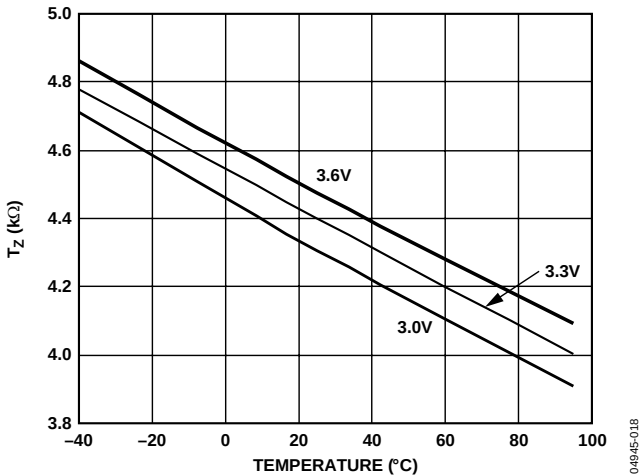


Figure 4. Differential Transimpedance vs. VCC and Temperature

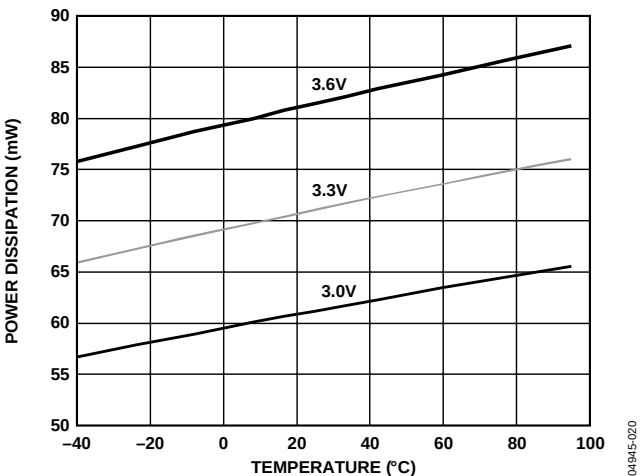


Figure 7. Power Dissipation vs. VCC and Temperature

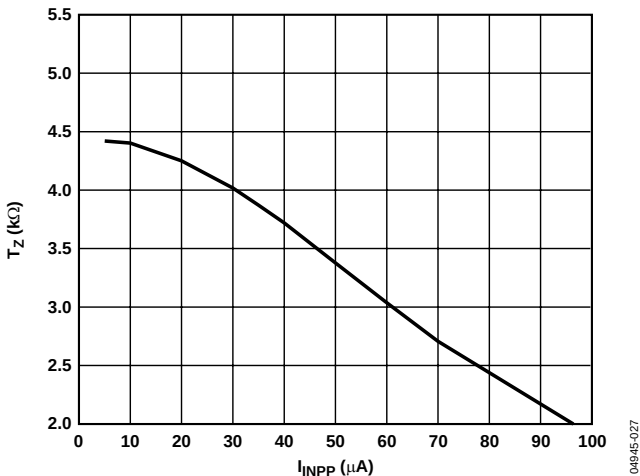


Figure 5. Differential Transimpedance vs. Input Current

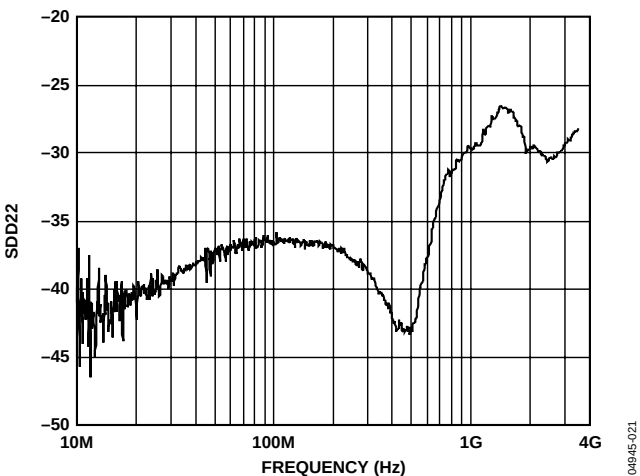


Figure 8. SDD22 vs. Frequency up to 3.5 GHz, CAP = Open

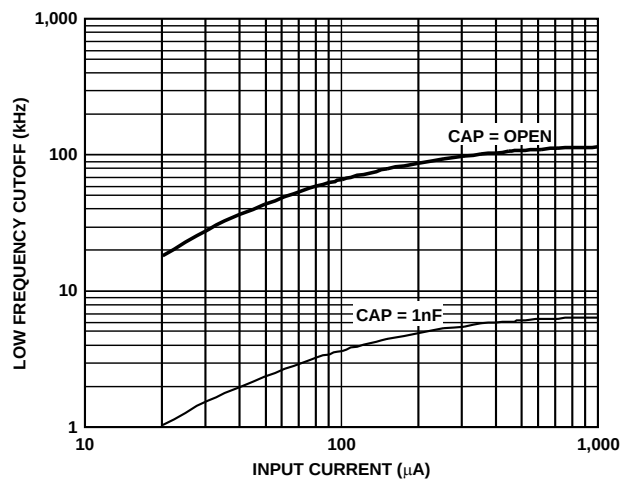


Figure 9. Low Frequency Cutoff vs. Input Current

04945-007

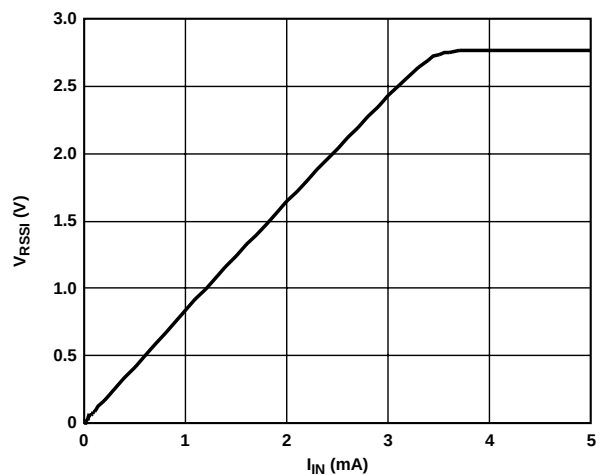


Figure 12. Full-Scale of RSSI Voltage Output vs. Input Current

04945-008

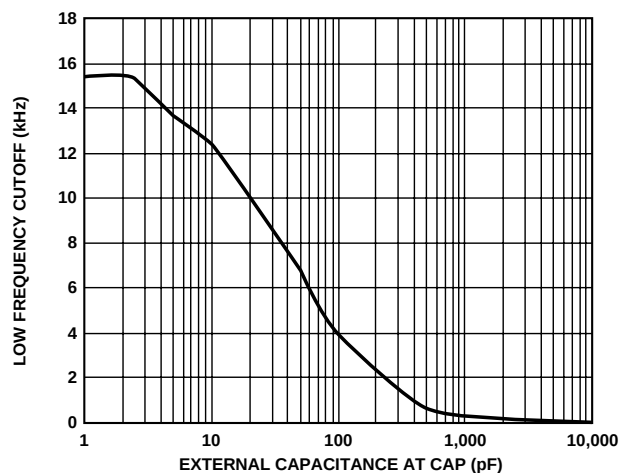


Figure 10. Low Frequency Cutoff vs. Capacitance at CAP

04945-031

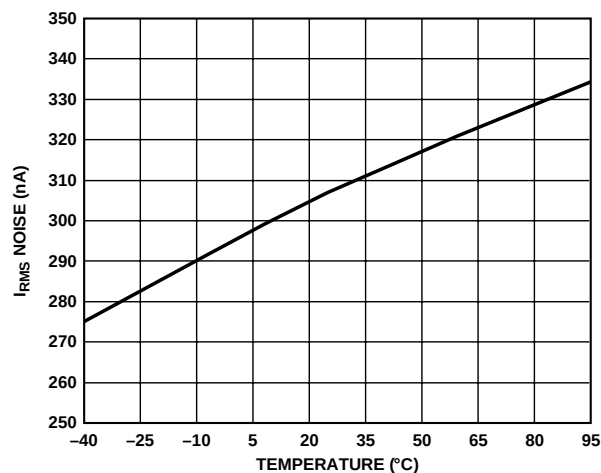
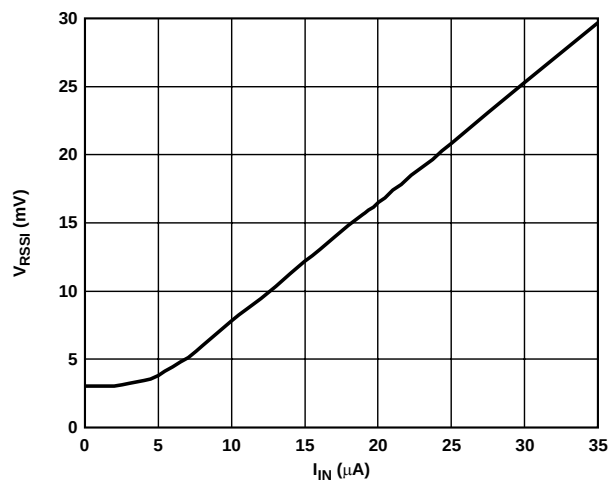
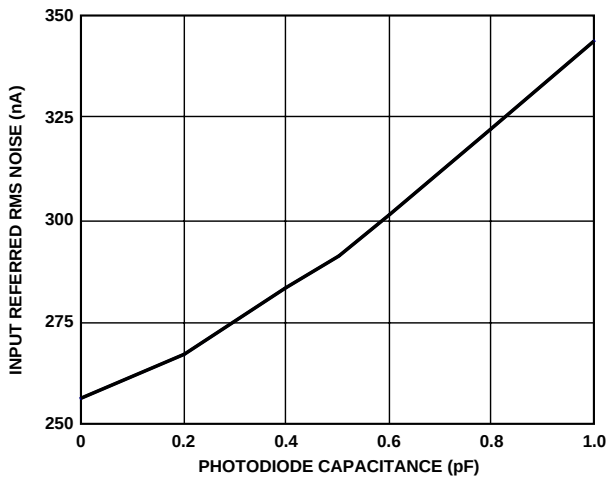


Figure 13. Input Noise vs. Temperature with 2 GHz Low-Pass Filter

04945-028

Figure 11. RSSI Voltage Output vs. Input Current (0 μ A to 35 μ A)

04945-024

Figure 14. Input Referred Noise (DC to 2.0 GHz) vs. Photodiode Capacitance C_D (pF)

04945-048

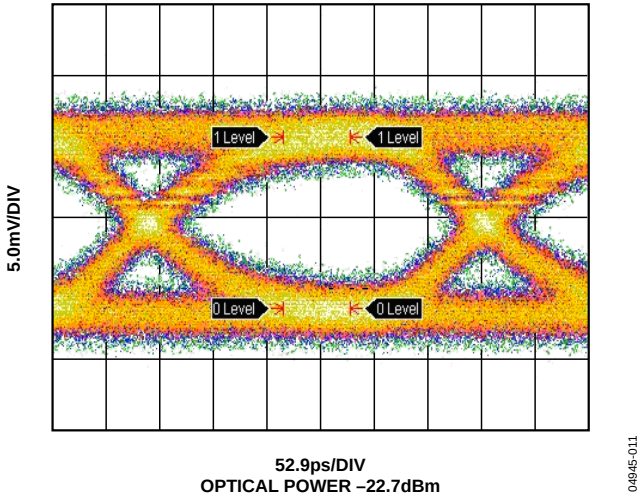


Figure 15. Output Eye at 3.2 Gbps with BER < 10^{-10} (Based on a 1550 nm PIN, Responsivity = 0.91 A/W, ER = 9 dB, PRBS 2^{31})

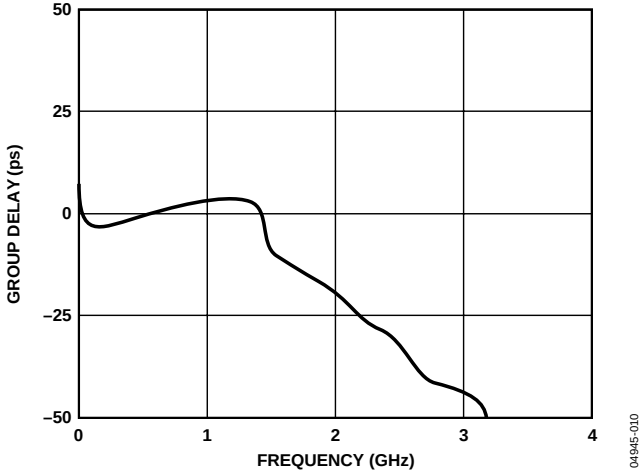


Figure 16. Group Delay vs. Frequency

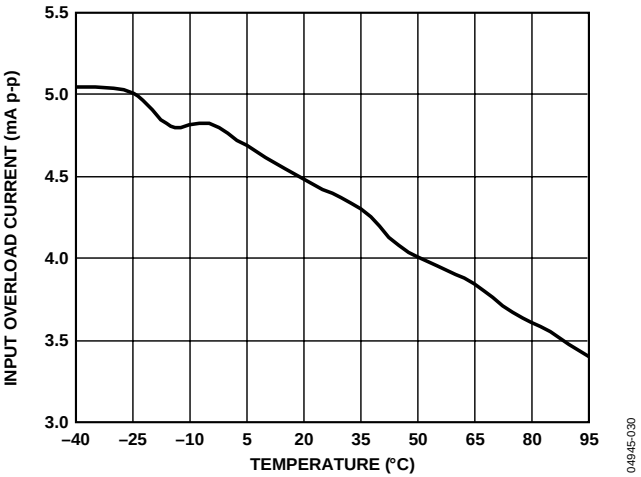


Figure 17. Input Overload Current vs. Temperature

ASSEMBLY RECOMMENDATIONS

Coplanar PIN Photodiode for SDH/SONET

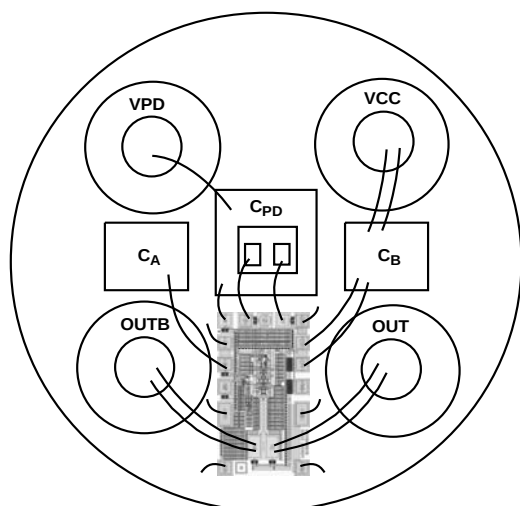


Figure 18. 5-Pin TO-46 with External Photodiode Supply V_{PD} Connected Through the FILTER Pin

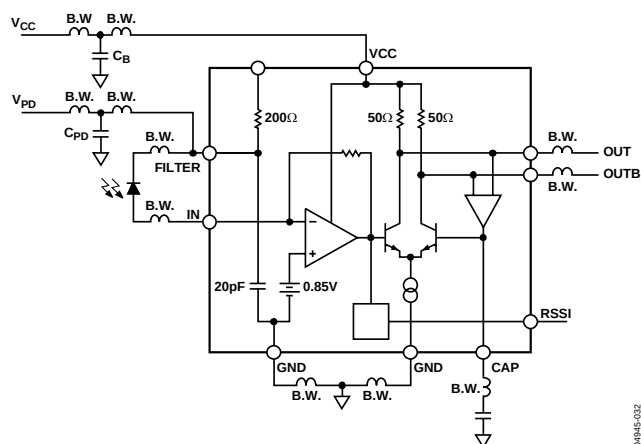


Figure 19. Equivalent Circuit of the Assembly Including Bond Wires

Dual Planar PIN/APD Photodiode for SDH/SONET

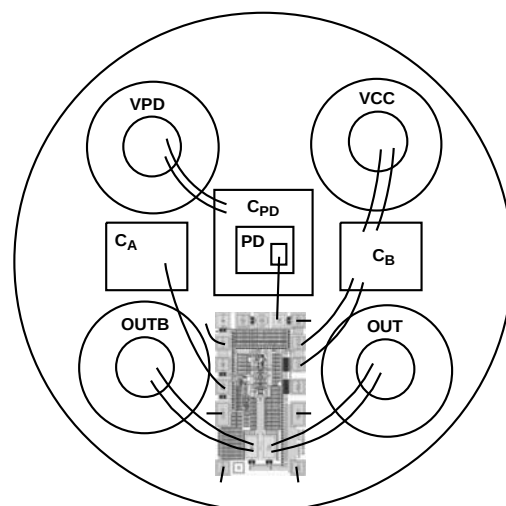


Figure 20. 5-Pin TO-46 with External Photodiode Supply V_{PD} to a Dual Planar PIN or APD

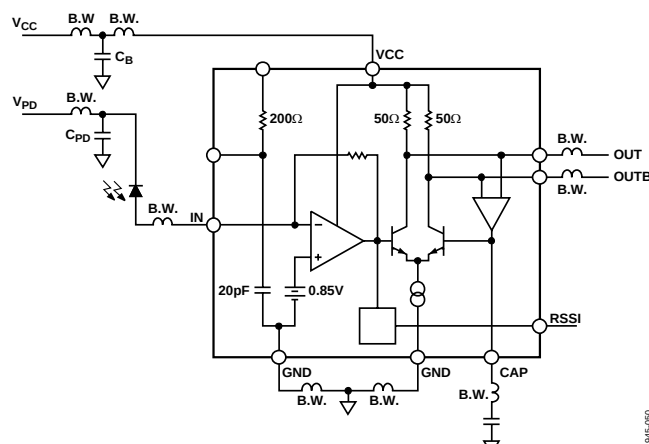


Figure 21. For Dual Planar PDs, No Connection to FILTER Pin

Table 4. Bill of Materials (BOM)

Component	Description
PD	1× vendor specific, 2.5 Gbps, photodiode
TIA	1× ADN2880 (0.7 mm × 1.2 mm), 3.2 Gbps, transimpedance amplifier
C_B	1× 200 pF, RF single-layer capacitor
C_{PD}	1× 560 pF, RF single-layer capacitor
C_A	1× 1000 pF, ceramic capacitor (optional for SDH)

Notes

One mil thickness, gold wire, ball bond recommended.

Minimize all GND bond-wire lengths.

Minimize IN, FILTER, OUT, and OUTB bond-wire lengths.

Maintain symmetry in length and orientation between OUT and OUTB bond wires.

Maintain symmetry in length and orientation between IN and FILTER bond wires.

Maintain symmetry between IN/FILTER and OUT/OUTB bond wires.

PIN Photodiode for a Non-SDH/SONET Application

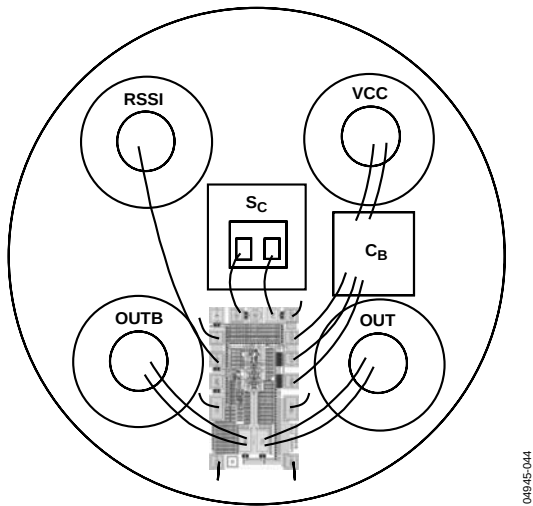


Figure 22. Coplanar PIN and RSSI Layout for a 5-Pin TO-46

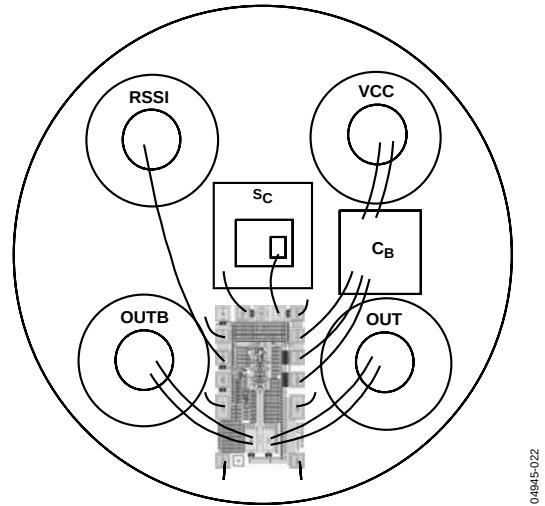


Figure 24. Dual Planar PIN and RSSI Layout for a 5-Pin TO-46

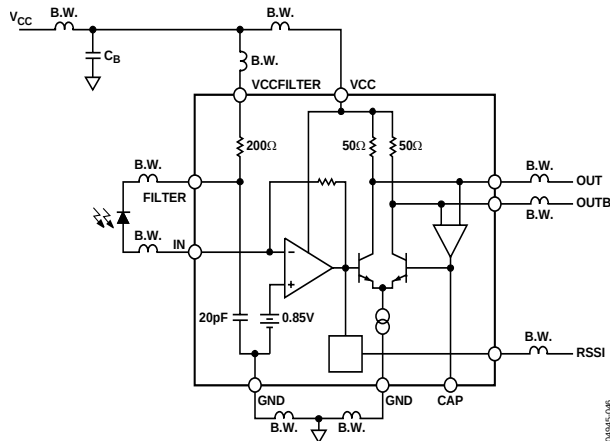


Figure 23. Equivalent Circuit with Bond Wires, as Shown in Figure 22

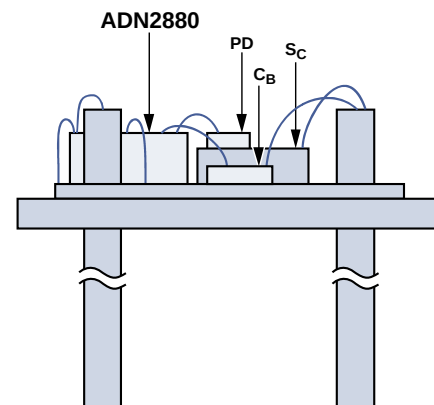


Figure 25. Side View of the Assembly, as Shown in Figure 22

Table 5. Bill of Materials (BOM)

Component	Description
PD	1× vendor specific, 2.5 Gbps, photodiode
TIA	1× ADN2880 (0.7 mm × 1.2 mm), 3.2 Gbps, transimpedance amplifier
C _B	1× 200 pF, RF single-layer capacitor
SC	1× ceramic standoff or 1× optional capacitor

Notes

One mil thickness, gold wire, ball bond recommended.

Minimize all GND bond-wire lengths.

Minimize IN, FILTER, OUT, and OUTB bond-wire lengths.

Maintain symmetry in length and orientation between OUT and OUTB bond wires.

Maintain symmetry in length and orientation between IN and FILTER bond wires.

Maintain symmetry between IN/FILTER and OUT/OUTB bond wires.

PIN Photodiode for Non-SDH/SONET Applications

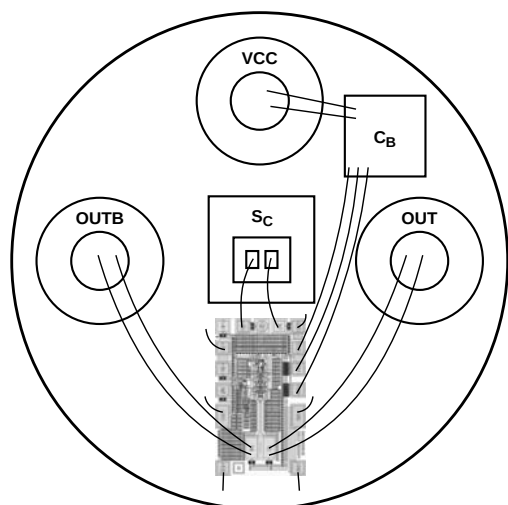


Figure 26. Coplanar PIN for a 4-Pin TO-46

04945-043

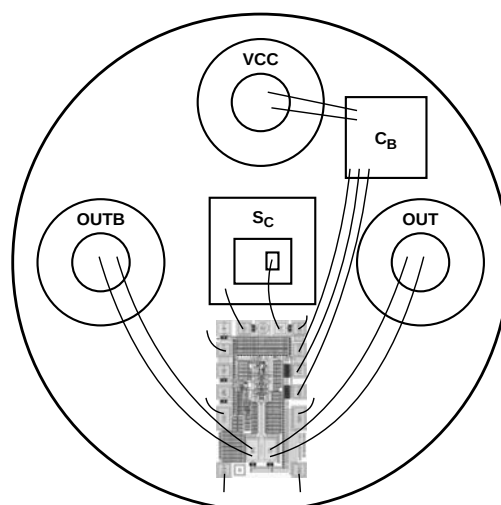


Figure 28. Dual Planar PIN for a 4-Pin TO-46

04945-051

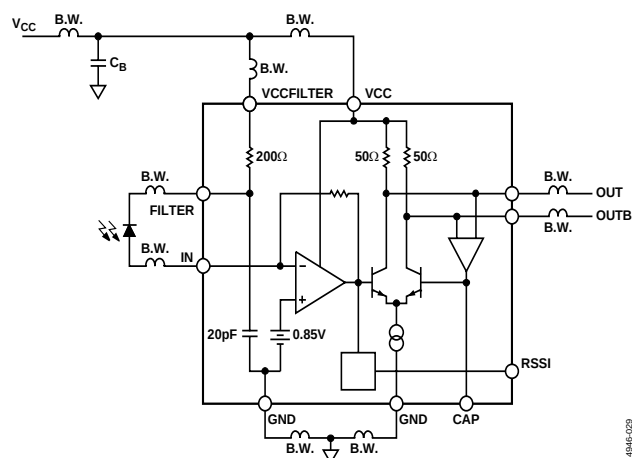


Figure 27. Equivalent Circuit with Bond Wires, as Shown in Figure 26

04945-029

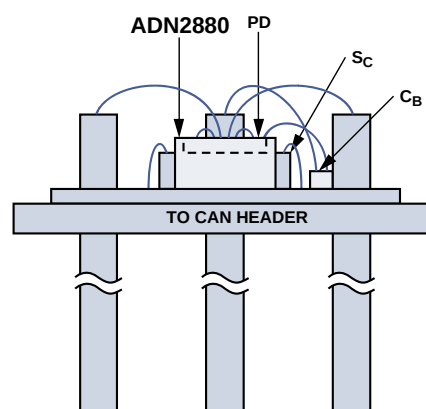


Figure 29. Side View of the Assembly, as Shown in Figure 26

04945-039

Table 6. Bill of Materials (BOM)

Component	Description
PD	1× vendor specific, 2.5 Gbps, photodiode
TIA	1× ADN2880 (0.7 mm × 1.2 mm), 3.2 Gbps, transimpedance amplifier
C _B	1× 200 pF, RF single-layer capacitor
S _C	1× ceramic standoff or 1× optional 1000 pF capacitor

Notes

One mil thickness, gold wire, ball bond recommended.

Minimize all GND bond-wire lengths.

Minimize IN, FILTER, OUT, and OUTB bond-wire lengths.

Maintain symmetry in length and orientation between OUT and OUTB bond wires.

Maintain symmetry in length and orientation between IN and FILTER bond wires.

Maintain symmetry between IN/FILTER and OUT/OUTB bond wires.

OUTLINE DIMENSIONS

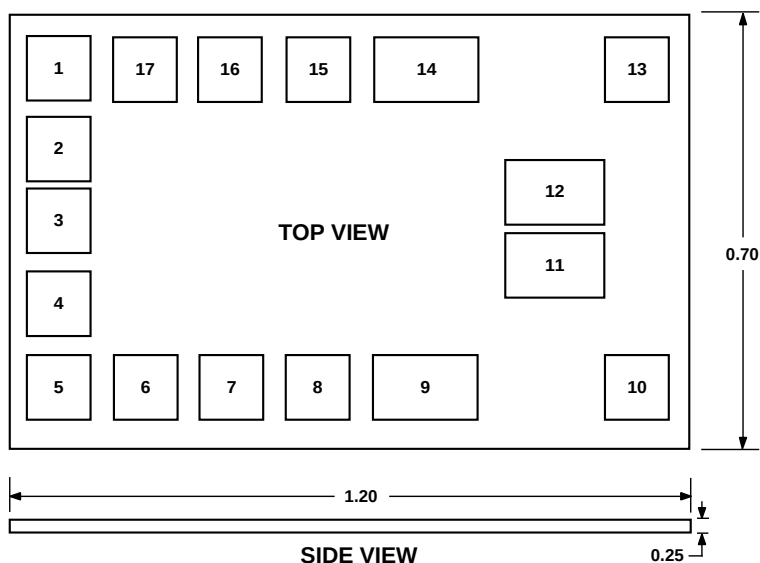


Figure 30. 17-Pad Bare Die Sales [CHIP]
Dimensions shown in millimeters

Table 7. Pad Coordinates

Pad No.	Mnemonic	X (μm)	Y (μm)
1	GND	-500	+260
2	IN	-500	+130
3	TEST	-500	+10
4	FILTER	-500	-120
5	FILTER	-500	-260
6	GND	-350	-260
7	RSSI	-200	-260
8	CAP	-50	-260
9	GND	+130	-260
10	GND	+500	-260
11	OUTB	+350	-60
12	OUT	+350	+60
13	GND	+500	+260
14	GND	+130	+260
15	VCCFILTER	-50	+260
16	VCC	-200	+260
17	VCC	-350	+260

DIE INFORMATION

Die Size

0.7 mm × 1.2 mm (edge-to-edge, including 1 mil scribe)

Die Thickness

10 mils = 0.25 mm

Passivation Openings

0.075 mm × 0.075 mm (Pad 1 to Pad 8, Pad 10, Pad 13,
Pad 15 to Pad 17)

0.144 mm × 0.075 mm (Pad 9, Pad 11, Pad 12, Pad 14)

Passivation Composition

5000 Å Si₃N₄ (top)

5000 Å SiO₂ (bottom)

Pad Composition

Al/1%Cu

Substrate Contact

To ground

ORDERING GUIDE

Model	Temperature	Package Description
ADN2880ACHIPS	-40°C to +95°C	17-Pad Die Sales